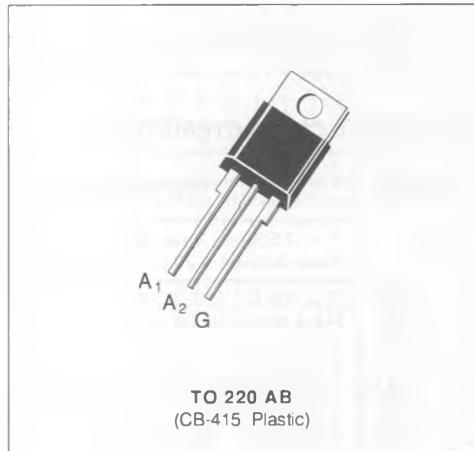


## SNUBBERLESS TRIACS

- $I_{TRMS} = 6 \text{ A}$  at  $T_c = 100^\circ\text{C}$ .
- $V_{DRM} : 200 \text{ V}$  to  $800 \text{ V}$ .
- $I_{GT} = 75 \text{ mA}$  (QI-II-III).
- GLASS PASSIVATED CHIP.
- HIGH SURGE CURRENT :  $I_{TSM} = 60 \text{ A}$ .
- HIGH COMMUTATION CAPABILITY :  
 $(di/dt)_c > 8 \text{ A/ms}$  without snubber.



### DESCRIPTION

New range suited for applications such as phase control and static switching on inductive or resistive load.

### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value		Unit
$I_{TRMS}$	RMS on-state current (360° conduction angle)	$T_c = 100^\circ\text{C}$	6	A
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = $25^\circ\text{C}$ )	$t = 8.3 \text{ ms}$	63	A
		$t = 10 \text{ ms}$	60	
$I^2 t$	$I^2 t$ value	$t = 10 \text{ ms}$	18	$\text{A}^2 \text{s}$
$di/dt$	Critical rate of rise of on-state current (1)	Repetitive $F = 50 \text{ Hz}$	20	$\text{A}/\mu\text{s}$
		Non Repetitive	100	
$T_{stg}$ $T_j$	Storage and operating junction temperature range	-40, +150 -40, +125		C

Symbol	Parameter	BTB 06-					Unit
		200 AW	400 AW	600 AW	700 AW	800 AW	
$V_{DRM}$	Repetitive peak off-state voltage (2)	±200	±400	±600	±700	±800	V

(1) Gate supply :  $I_G = 750 \text{ mA} - di_G / dt = 1 \text{ A}/\mu\text{s}$

(2)  $T_j = 125^\circ\text{C}$

## THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R <sub>th</sub> (j - a)	Junction to ambient	60	°C/W
R <sub>th</sub> (j - c) DC	Junction to case for DC	3.5	°C/W
R <sub>th</sub> (j - c) AC	Junction to case for 360 ° conduction angle (F = 50 Hz)	2.7	°C/W

## GATE CHARACTERISTICS (maximum values)

P<sub>GM</sub> = 40 W (t = 10 µs)   P<sub>G (AV)</sub> = 1 W   I<sub>GM</sub> = 4 A (t = 10 µs)   V<sub>GM</sub> = 16 V (t = 10 µs).

## ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions		Quadrants	Min.	Typ.	Max.	Unit
I <sub>GT</sub>	T <sub>j</sub> = 25 °C	V <sub>D</sub> = 12 V	R <sub>L</sub> = 33 Ω	I-II-III	2	75	mA
	Pulse duration > 20 µs						
V <sub>GT</sub>	T <sub>j</sub> = 25 °C	V <sub>D</sub> = 12 V	R <sub>L</sub> = 33 Ω	I-II-III		1.5	V
	Pulse duration > 20 µs						
V <sub>GD</sub>	T <sub>j</sub> = 125 °C	V <sub>D</sub> = V <sub>DRM</sub>	R <sub>L</sub> = 3.3 kΩ	I-II-III	0.2		V
	Pulse duration > 20 µs						
I <sub>H</sub> *	T <sub>j</sub> = 25 °C Gate open	I <sub>T</sub> = 100 mA R <sub>L</sub> = 140 Ω				75	mA
I <sub>L</sub>	T <sub>j</sub> = 25 °C Pulse duration > 20 µs	V <sub>D</sub> = 12 V	I <sub>G</sub> = 500 mA	I-III	75		
				II	150		
V <sub>TM</sub> *	T <sub>j</sub> = 25 °C	I <sub>TM</sub> = 8.5 A	t <sub>p</sub> = 10 ms			1.75	V
I <sub>DRM</sub> *	T <sub>j</sub> = 25 °C T <sub>j</sub> = 125 °C	V <sub>DRM</sub> rated	Gate open			0.01	
						2	
dV/dt*	T <sub>j</sub> = 125 °C Linear slope up to 0.67 V <sub>DRM</sub>	Gate open		750	1000		V/µs
(di/dt) <sub>c</sub> *	T <sub>j</sub> = 125 °C Without snubber	V <sub>DRM</sub> rated			8	16	A/ms
t <sub>gt</sub>	T <sub>j</sub> = 25 °C I <sub>T</sub> = 8.5 A	di <sub>G</sub> /dt = 3.5 A/µs V <sub>D</sub> = V <sub>DRM</sub>	I <sub>G</sub> = 500 mA	I-II-III	2		µs

\* For either polarity of electrode A<sub>2</sub> voltage with reference to electrode A<sub>1</sub>.

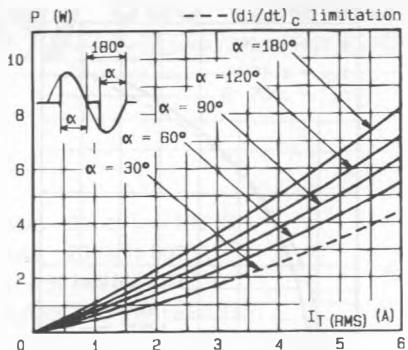


Fig.1 - Maximum mean power dissipation versus RMS on-state current ( $f = 60$  Hz).

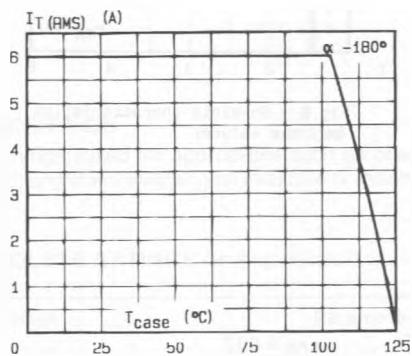


Fig.3 - RMS on-state current versus case temperature.

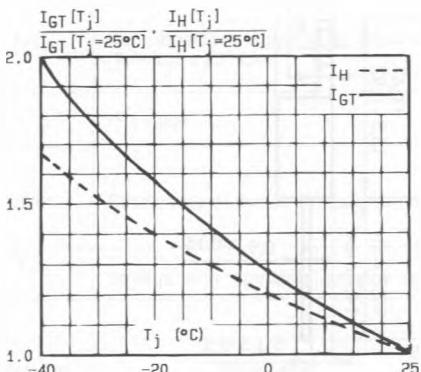


Fig 5 - Relative variation of gate trigger current and holding current versus junction temperature.

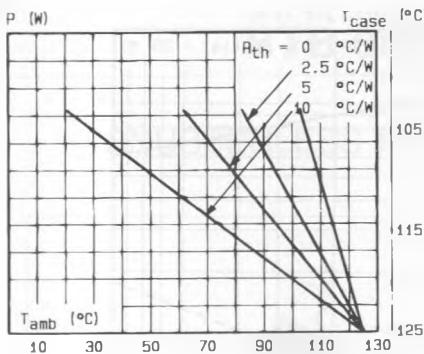


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact.

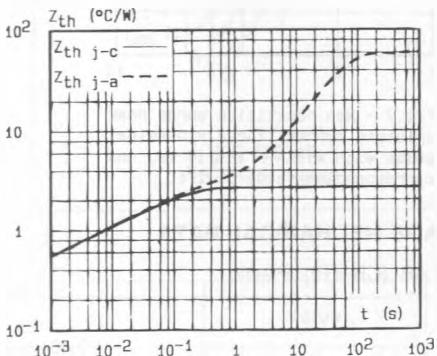


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

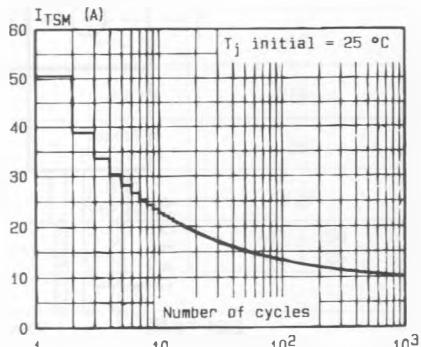


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

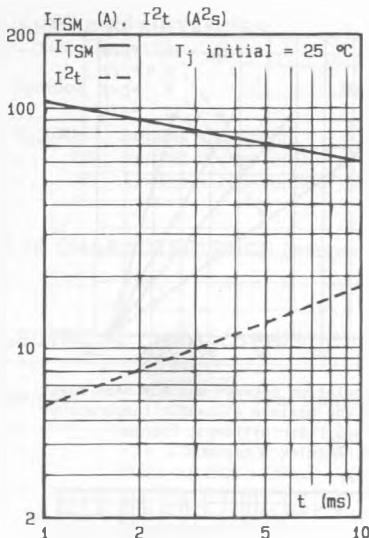


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10$  ms, and corresponding value of  $I^2t$ .

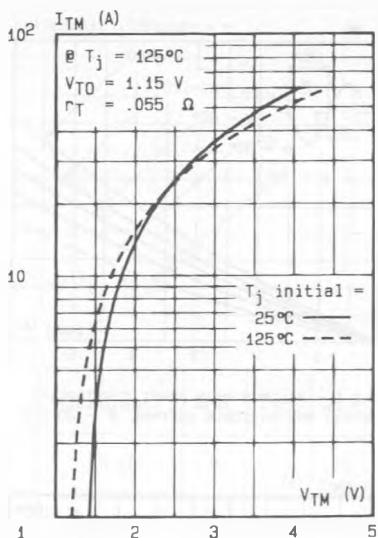
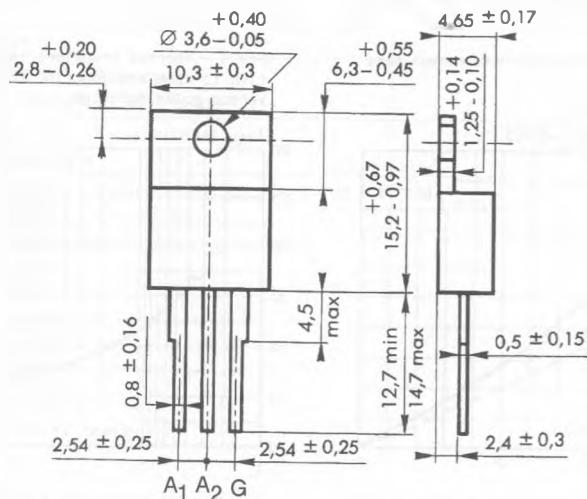


Fig.8 - On-state characteristics (maximum values).

## PACKAGE MECHANICAL DATA

TO 220 AB (CB-415) Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g